Product Preview **500 mA, 40 V Schottky Barrier Diode**

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current that offers the most optimal power dissipation in applications. They are housed in spacing saving micro–packaging ideal for space constraint applications.

Features

- Low Forward Voltage Drop 560 mV (Typ.) @ $I_F = 500 \text{ mA}$
- Low Reverse Current $3.0 \,\mu\text{A}$ (Typ.) @ V_R = $40 \,\text{V}$
- 500 mA of Continuous Forward Current
- High Switching Speed
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

MAXIMUM RATINGS

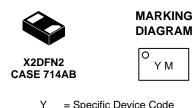
Rating	Symbol	Value	Unit
Reverse Voltage	V _R	40	V
Forward Current (DC)	١ _F	500	mA
Forward Surge Current (60 Hz @ 1 cycle)	I _{FSM}	2.5	A
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I _{FRM}	0.6	A
ESD Rating: Human Body Model Charged Device Model	ESD	> 8 > 1	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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Y = Specific Device Code M = Date Code

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ORDERING INFORMATION

Device	Package	Shipping [†]
NSR05T404MXT5G	X2DFN2 (Pb–Free)	2 mm Pitch 8000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

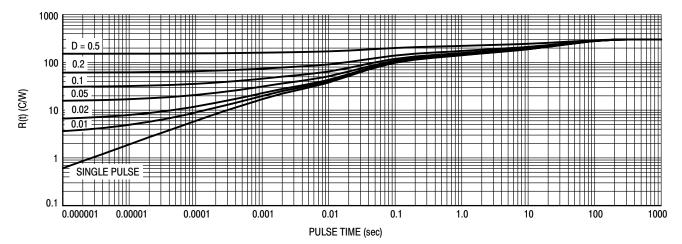
This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction–to–Ambient (Note 1) Total Power Dissipation @ $T_A = 25^{\circ}C$	R _{θJA} P _D			310 480	°C/W mW
Thermal Resistance Junction–to–Ambient (Note 2) Total Power Dissipation @ $T_A = 25^{\circ}C$	R _{θJA} PD			150 1000	°C/W mW
Junction and Storage Temperature Range	T _J , T _{stg}		-55 to +150		°C

1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

2. Mounted onto a 4 in square FR-4 board 650 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.





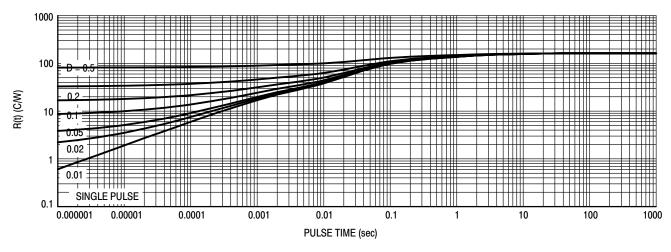


Figure 2. Thermal Response (Note 2)

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage $(V_R = 10 V)$ $(V_R = 40 V)$	۱ _R		0.2 3.0	3.1 85	μΑ
Forward Voltage $(I_F = 10 \text{ mA})$ $(I_F = 100 \text{ mA})$ $(I_F = 200 \text{ mA})$ $(I_F = 500 \text{ mA})$	VF		370 450 490 560	400 480 530 630	mV
Total Capacitance $(V_R = 1.0 \text{ V}, \text{ f} = 1.0 \text{ MHz})$	CT		50		pF
Reverse Recovery Time $(I_F = I_R = 10 \text{ mA}, I_{R(REC)} = 1.0 \text{ mA}, Figure 3)$	t _{rr}		13		ns
Peak Forward Recovery Voltage $(I_F = 100 \text{ mA}, t_r = 20 \text{ ns}, \text{Figure 4})$	V _{FRM}		600		mV

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

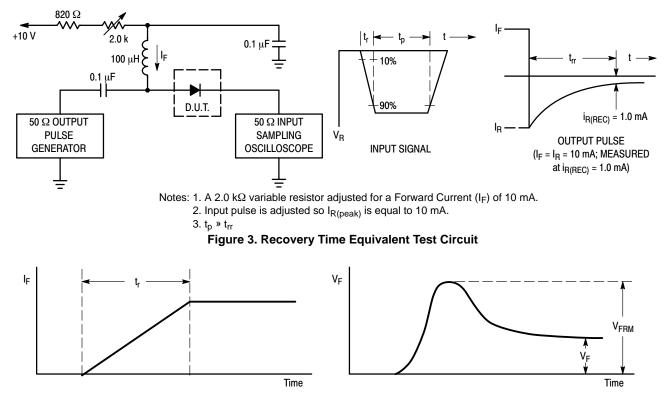
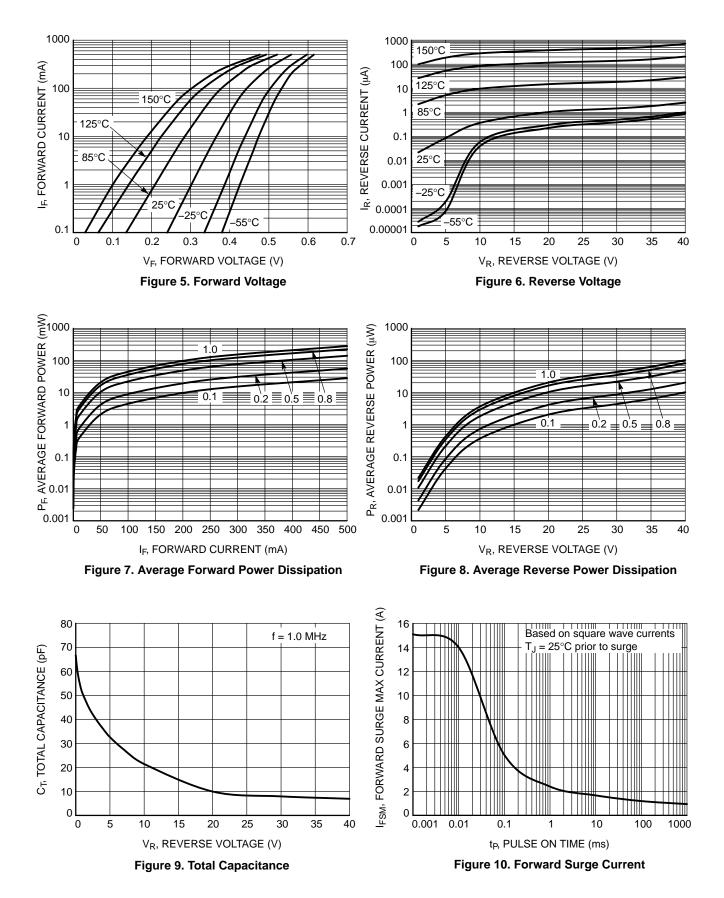


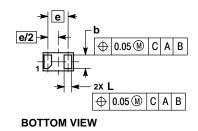
Figure 4. Peak Forward Recovery Voltage Definition

TYPICAL CHARACTERISTICS



PACKAGE DIMENSIONS

X2DFN2 1.0x0.6, 0.65P CASE 714AB **ISSUE A** \square 0.10 C AB D PIN 1 INDICATOR Ε 0.05 C \frown TOP VIEW NOTE 3 0.10 C 0.10 C \cap Δ1 SEATING C PLANE SIDE VIEW



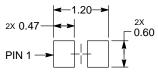
NOTES: 1. DIMENSIONING AND TOLERANCING PER

ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.

CONTROLLING DIMENSION: MILLIMETERS
EXPOSED COPPER ALLOWED AS SHOWN.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.34	0.40	
A1		0.05	
b	0.45	0.55	
D	1.00 BSC		
E	0.60 BSC		
е	0.65 BSC		
L	0.20	0.30	

RECOMMENDED SOLDER FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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